RELIABILITY REPORT

FOR

MAX9031AxK

PLASTIC ENCAPSULATED DEVICES

August 15, 2006

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by

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Conclusion

The **MAX9031** successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX9031 single/dual/quad comparator is optimized for single-supply applications from +2.5V to +5.5V but can also be operated from dual supplies. This comparator has a 188ns propagation delay and consume 35µA of supply current per comparator over the -40°C to +125°C operating temperature range. The combination of low-power, single-supply operation down to +2.5V, and ultra-small footprint makes this device ideal for portable applications.

The MAX9031 is low-cost single, dual, and quad comparator without shutdown, respectively. The comparators' 4mV of built-in hysteresis provides noise immunity and prevents oscillations even with a slow-moving input signal. The input common-mode range extends from the negative supply to within 1.1V of the positive supply. The design of the comparator output stage substantially reduces switching current during output transitions, virtually eliminating power-supply glitches.

The MAX9031 single comparator is available in tiny 5-pin SC70 and SOT23 packages.

B. Absolute Maximum Ratings

Item	Rating
Supply Voltage (VDD to VSS)	-0.3V to +6V
Voltage Inputs (IN+, IN- to VSS)	0.3V to (VDD + 0.3V)
Differential Input Voltage (IN+ to IN-)	+6.6V
Output Short-Circuit Duration	2s to Either VDD or VSS
Current into Any Pin	20mA
Continuous Power Dissipation (TA = +70°C)	
5-Pin SC70 (derate 3.1mW/°C above +70°C)	247mW
5-Pin SOT23 (derate 7.1mW/°C above +70°C)	571mW
Operating Temperature Range	
Automotive Application	-40°C to +125°C
Junction Temperature	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C

II. Manufacturing Information

A. Description/Function: Low-Cost, Ultra-Small, Single/Dual/Quad Single-Supply Comparators

B. Process: B12 (Standard 1.2 micron silicon gate CMOS)

C. Number of Device Transistors: 123

D. Fabrication Location: California or Texas, USA

E. Assembly Location: Malaysia, Philippines or Thailand

F. Date of Initial Production: July, 2000

III. Packaging Information

A. Package Type:	**5-pin SC70**	**5-Pin SOT23**
B. Lead Frame:	Copper or Alloy 42	Copper
C. Lead Finish:	Solder Plate or 100% Matte Tin	Solder Plate or 100% Matte Tin
D. Die Attach:	Silver-filled Epoxy	Silver-filled Epoxy
E. Bondwire:	Gold (1 mil dia.)	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	# 05-1501-0194	# 05-1501-0192
H. Flammability Rating:	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C:	Level 1	Level 1

IV. Die Information

A. Dimensions: 31 x 30 mils

B. Passivation: Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)

C. Interconnect: Aluminum/Si (Si = 1%)

D. Backside Metallization: None

E. Minimum Metal Width: 1.2 microns (as drawn)

F. Minimum Metal Spacing: 1.2 microns (as drawn)

G. Bondpad Dimensions: 5 mil. Sq.

H. Isolation Dielectric: SiO_2

I. Die Separation Method: Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts: Jim Pedicord (Manager, Reliability Operations)
Bryan Preeshl (Managing Director of QA**)**

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 80 \times 2}$$ (Chi square value for MTTF upper limit)

Temperature Acceleration factor assuming an activation energy of 0.8eV

$\lambda = 13.76 \times 10^{-9}$

λ = 13.76 F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability monitor program. In addition to routine production Burn-In, Maxim pulls a sample from every fabrication process three times per week and subjects it to an extended Burn-In prior to shipment to ensure its reliability. The reliability control level for each lot to be shipped as standard product is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Attached Burn-In Schematic (Spec. # 06-5494) shows the static Burn-In circuit. Maxim performs failure analysis on any lot that exceeds this reliability control level. Maxim also performs quarterly 1000 hour life test monitors. This data is published in the Product Reliability Report (**RR-1N**). Current monitor data for the B8/S8 Process results in a FIT rate of 0.10 @ 25°C and 1.78 @ 55°C (eV = 0.8, UCL = 60%).

B. Moisture Resistance Tests

Maxim pulls pressure pot samples from every assembly process three times per week. Each lot sample must meet an LTPD = 20 or less before shipment as standard product. Additionally, the industry standard 85°C/85%RH testing is done per generic device/package family once a quarter.

C. E.S.D. and Latch-Up Testing

The CM51Z die type has been found to have all pins able to withstand a transient pulse of ±2500V, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±250mA.

Table 1
Reliability Evaluation Test Results

MAX9031AxK

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		80	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	SOT SC70	77 77	0 0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground

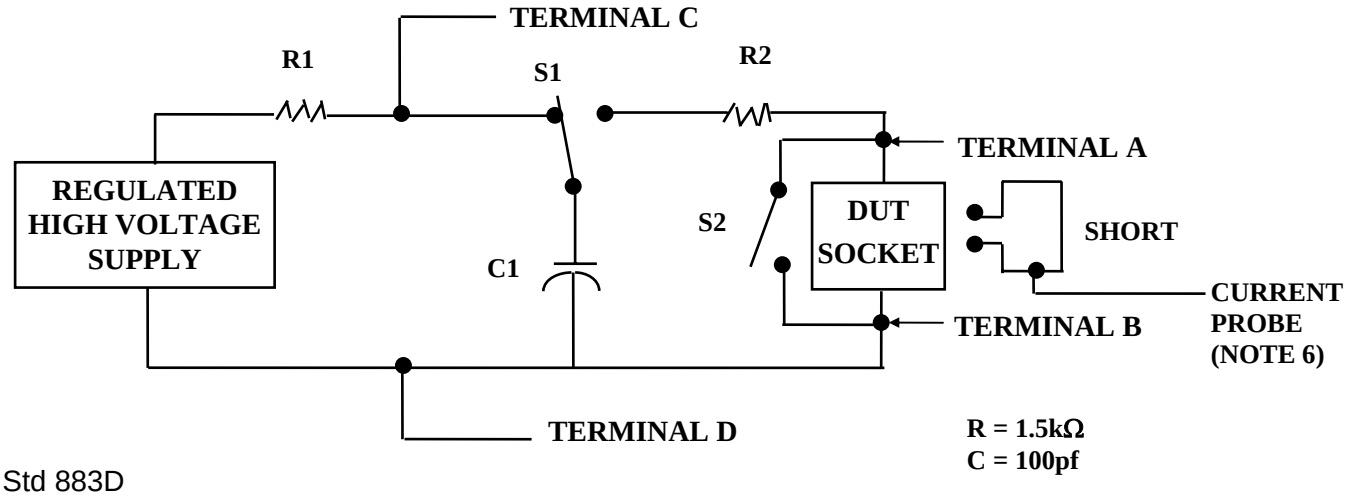
(e.g., where V_{PS1} is V_{DD}, V_{CC}, V_{SS}, V_{BB}, GND, $+V_S$, $-V_S$, V_{REF}, etc).

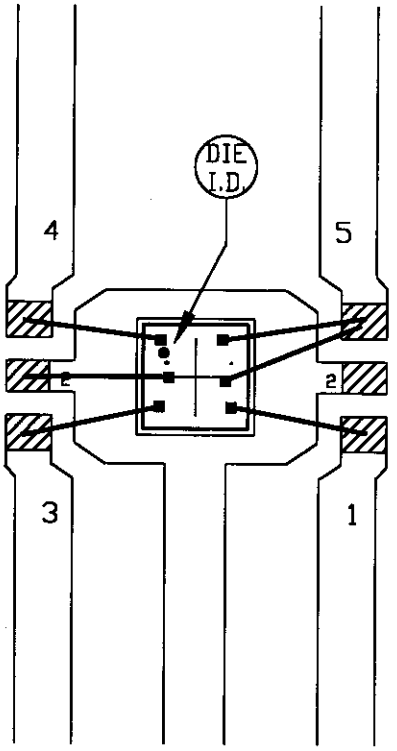
3.4 Pin combinations to be tested.

a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.

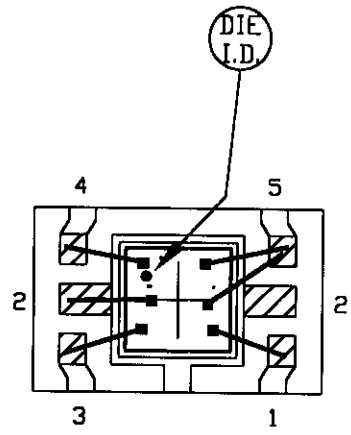




▨ - BONDING AREA

NOTE: CAVITY DOWN

PKG. CODE: U5-1		SIGNATURES	DATE	MAXIM CONFIDENTIAL & PROPRIETARY	
CAV./PAD SIZE: 64X45	PKG.		2/2/00	BOND DIAGRAM #: 05-1501-0192	REV: A
	DESIGN	As per faxed copy	2/1/00		



▨ BONDABLE AREA

NOTE: CAVITY DOWN

PKG. CODE: X5-1		SIGNATURES	DATE	MAXIM CONFIDENTIAL & PROPRIETARY
CAV./PAD SIZE: 35x34	PKG.		2/2/00	BOND DIAGRAM #: 05-1501-0194 / REV: A
	DESIGN			